

Automotive IPD 1ch Low Side Switch

BV1LC085EFJ-C

Features

- AEC-Q100 Qualified*1
- Built-in Over Current Protection Function(OCP)
- Built-in Thermal Shutdown Function (TSD)
- Built-in Active Clamp Function
- Built-in Diagnostic Function
- Direct Control Enabled from CMOS Logic IC, etc.
- On Resistance $R_{DS(ON)} = 85 \text{ m}\Omega$ (Typ)
(when $V_{IN} = 5 \text{ V}$, $I_{OUT} = 0.8 \text{ A}$, $T_j = 25 \text{ }^\circ\text{C}$)
- Monolithic Power Management IC with the Control Block (CMOS) and Power MOS FET Mounted on a Single Chip

*1 Grade1

Key Specifications

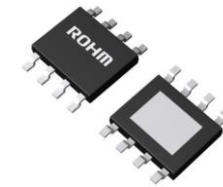
On-state Resistance ($T_j = 25 \text{ }^\circ\text{C}$, Typ)	85 m Ω
Over Current Limitation Level ($T_j = 25 \text{ }^\circ\text{C}$, Typ)	5.5 A
Output Clamp Voltage (Min)	42 V
Active Clamp Energy ($T_{j(\text{START})} = 25 \text{ }^\circ\text{C}$)	400 mJ

Package

HTSOP-J8

W (Typ) x D (Typ) x H (Max)

4.9 mm x 6.0 mm x 1.00 mm



General Description

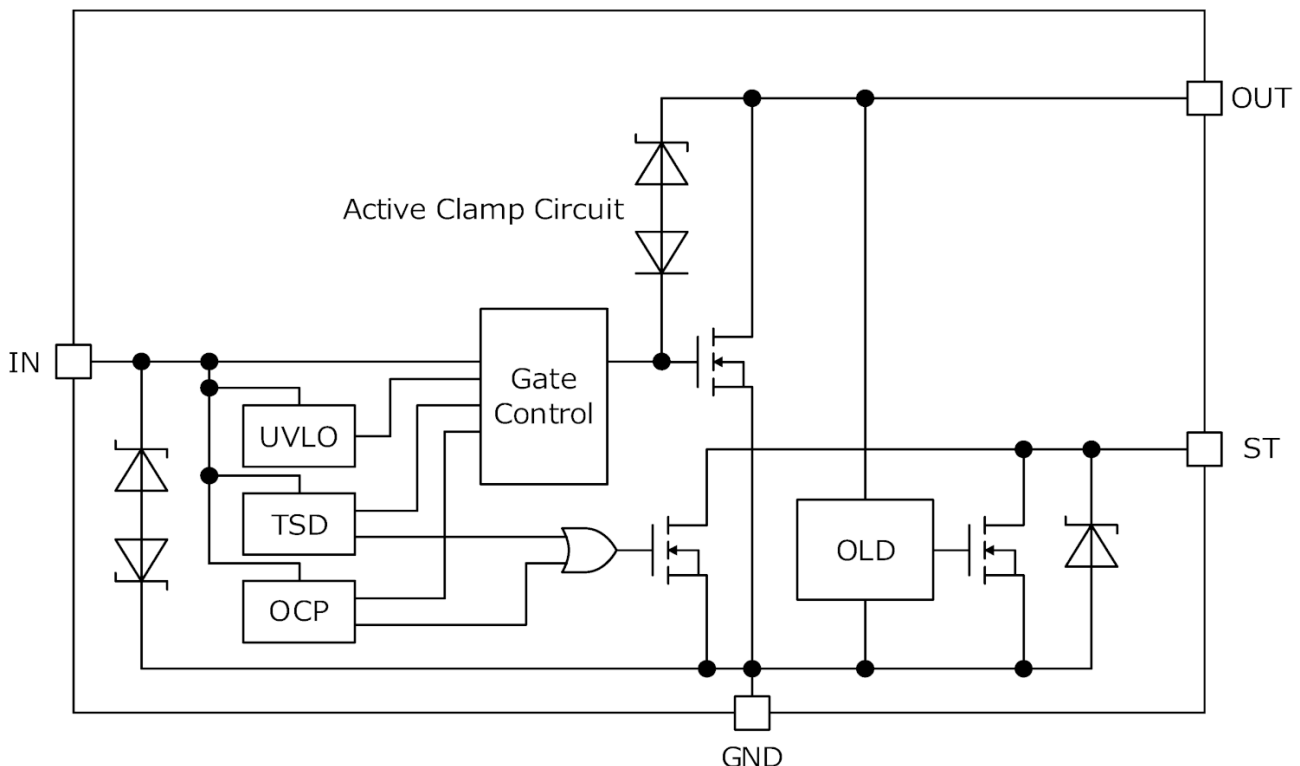
The BV1LC085EFJ-C is an automotive 1ch low side switch IC, which has built-in OCP, TSD, active clamp function.

Also, diagnostic function can diagnose OCP, TSD, open load detection function (OLD).

Application

- Driving Resistive, Inductive and Capacitive Load

Block Diagram

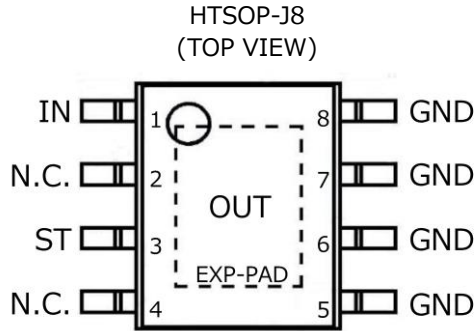


○Product structure : Silicon integrated circuit ○This product has no designed protection against radioactive rays.

Contents

Features.....	1
General Description	1
Application	1
Key Specifications.....	1
Package	1
Block Diagram.....	1
Contents	2
Pin Configuration.....	3
Pin Description	3
Term.....	3
Absolute Maximum Ratings.....	4
Recommended Operating Conditions.....	5
Thermal Resistance	5
Electrical Characteristics	9
Typical Performance Curves	11
Measurement Circuit for Typical Performance Curves	17
I/O Pin Truth Table	20
Timing Chart.....	20
Function Description	22
Operational Notes.....	24
Ordering Information	26
Marking Diagram.....	26
Physical Dimension and Packing Information.....	27
Revision History	28

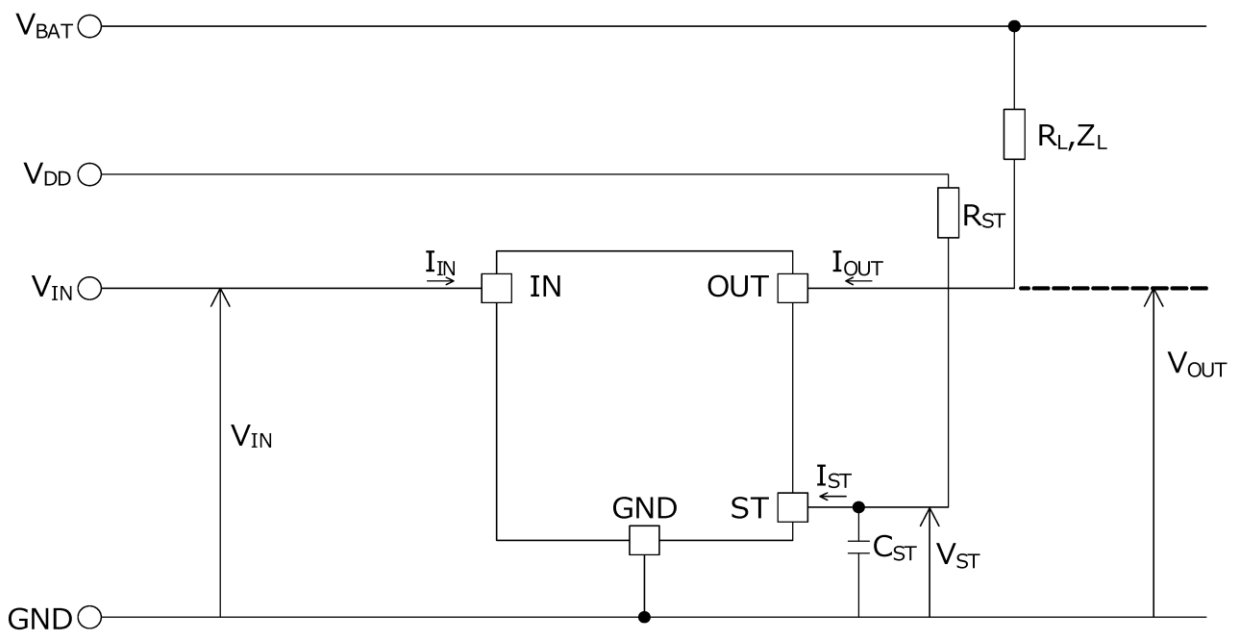
Pin Configuration



Pin Description

Pin No.	Pin Name	Function
1	IN	Input pin, with internal pull-down resistor.
2	N.C.	Not connected to internal circuit. Be open, connected to GND or connected IN.
3	ST	Self-diagnostic output pin.
4	N.C.	Not connected to internal circuit. Be open, connected to GND or connected IN.
5	GND	GND pin.
6	GND	GND pin.
7	GND	GND pin.
8	GND	GND pin.
EXP-PAD	OUT	Output pin. When output pin shorted to battery, output current is limited to protect IC.

Term



Absolute Maximum Ratings(Tj = 25 °C)

Parameter	Symbol	Ratings	Unit
Output Voltage	V _{OUT}	-0.3 to +42	V
Input Voltage	V _{IN}	-0.3 to +7	V
Output Current	I _{OUT}	4 (inside limited) ^{*1}	A
Diagnostic Output Voltage	V _{ST}	-0.3 to +7	V
Diagnostic Output Current	I _{ST}	10	mA
Active Clamp Energy (Single Pulse) T _{j(START)} = 25 °C, I _{OUT(START)} = 1.5 A	E _{AS(25 °C)}	400	mJ
Active Clamp Energy (Single Pulse) T _{j(START)} = 150 °C, I _{OUT(START)} = 1.5 A ^{*2}	E _{AS(150 °C)}	140	
Operating Temperature Range	T _j	-40 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Maximum Junction Temperature	T _{jmax}	150	°C

*1 Internally limited by over current protection function.

*2 Not 100 % tested.

Caution 1: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Caution 2: Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.

Caution 3: When IC turns off with an inductive load, reverse energy has to be dissipated in the IC. This energy can be calculated by the following equation:

$$E_L = \frac{1}{2} L I_{OUT(START)}^2 \times \left(1 - \frac{V_{BAT}}{V_{BAT} - V_{OUT(CL)}} \right)$$

Where:

L is the inductance of the inductive load.

I_{OUT(START)} is the output current at the time of turning off.

V_{OUT(CL)} is the output clamp voltage.

The IC integrates the active clamp function to internally absorb the reverse energy E_L which is generated when the inductive load is turned off. When the active clamp operates, the thermal shutdown function does not work. Decide a load so that the reverse energy E_L is active clamp tolerance E_{AS} (refer to Figure 1.) or under when inductive load is used.

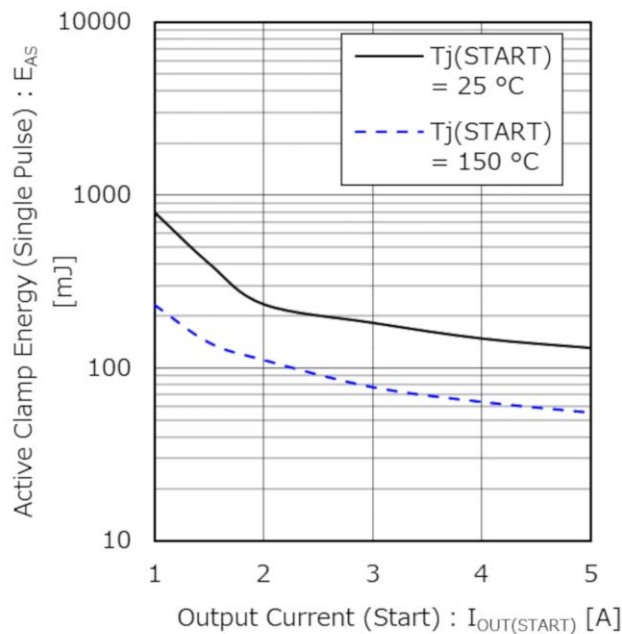


Figure 1. Active Clamp Energy (Single Pulse) vs Output Current (Start)

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Input Voltage	V _{IN}	3.0	5.0	5.5	V
Operating Temperature	T _j	-40	+25	+150	°C

Thermal Resistance*1

Parameter	Symbol	Typ	Unit	Condition
BV1LC085EFJ-C				
Between Junction and Surroundings Temperature Thermal Resistance	θ _{JA}	126.5	°C/W	1s *2
		37.3	°C/W	2s *3
		25.0	°C/W	2s2p *4

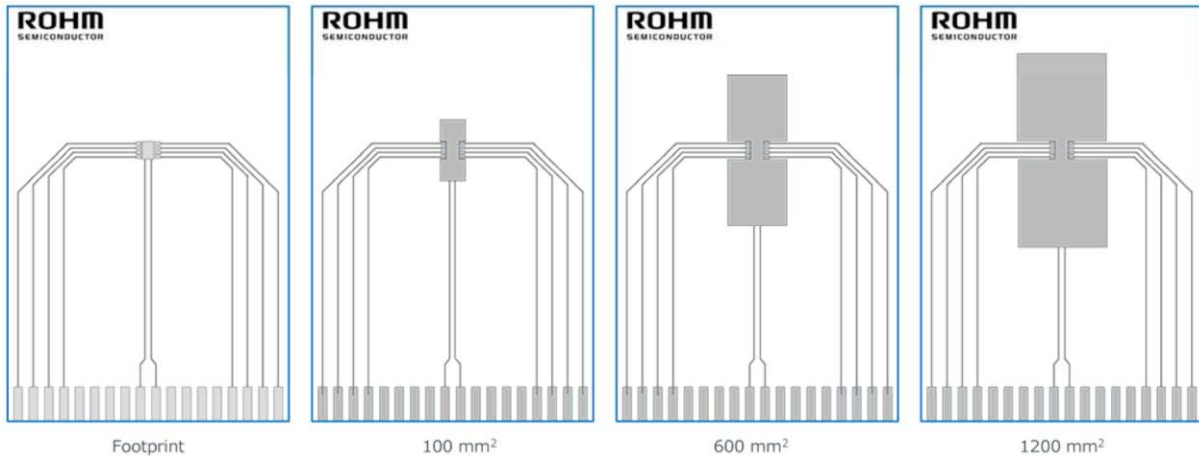
*1 The thermal impedance is based on JESD51-2A (Still-Air) standard. It is used the chip of BV1LC085EFJ-C.

*2 JESD51-3 standard FR4 114.3 mm x 76.2 mm x 1.57 mm 1-layer (1s)
 (Top copper foil: ROHM recommended Footprint + wiring to measure, 2 oz. copper.)

*3 JESD51-5 standard FR4 114.3 mm x 76.2 mm x 1.60 mm 2-layers (2s)
 (Top copper foil: ROHM recommended Footprint + wiring to measure/
 Copper foil area on the reverse side of PCB: 74.2 mm x 74.2 mm,
 copper (top & reverse side) 2 oz.)

*4 JESD51-5/-7 standard FR4 114.3 mm x 76.2 mm x 1.60 mm 4-layers (2s2p)
 (Top copper foil: ROHM recommended Footprint + wiring to measure/
 2 inner layers and copper foil area on the reverse side of PCB: 74.2 mm x 74.2 mm,
 copper (top & reverse side/inner layers) 2 oz./1 oz.)

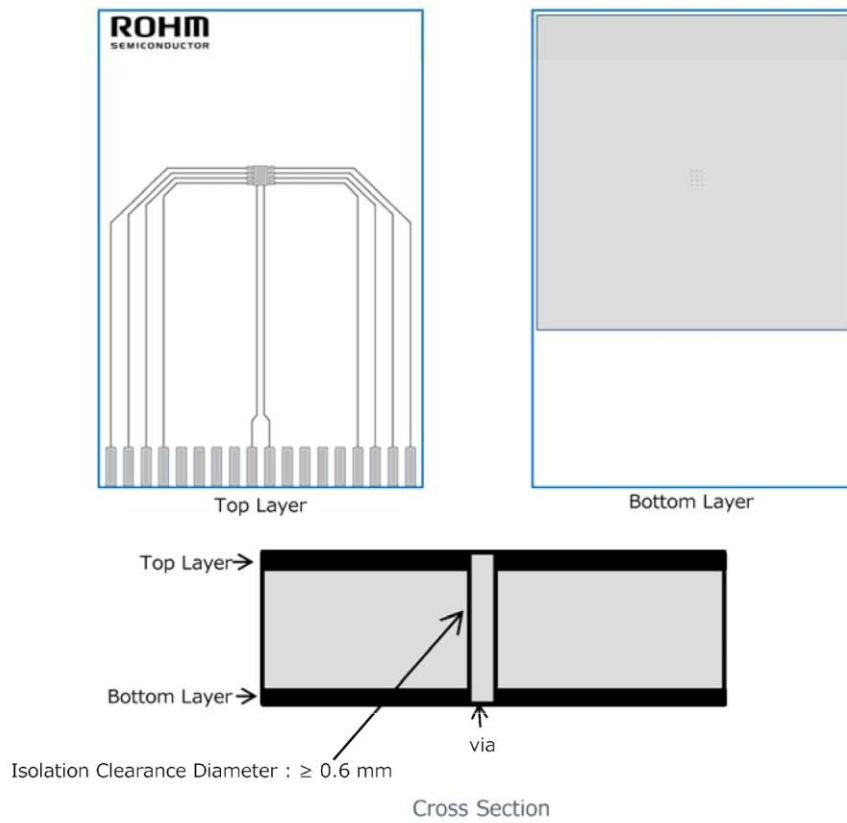
■ PCB Layout 1 layer (1s)



Dimension	Value
Board Finish Thickness	1.57 mm ± 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top Layer)	0.070 mm (Cu:2 oz)
Copper Foil Area Dimension	Footprint / 100 mm² / 600 mm² / 1200 mm²

Thermal Resistance – continued

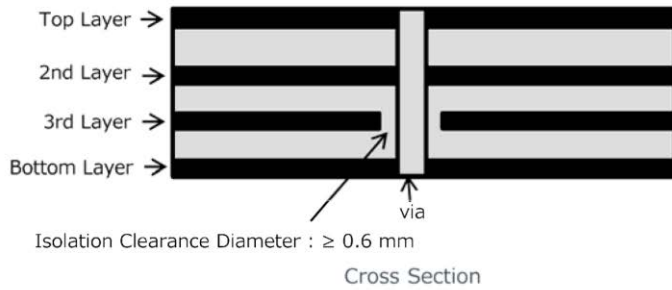
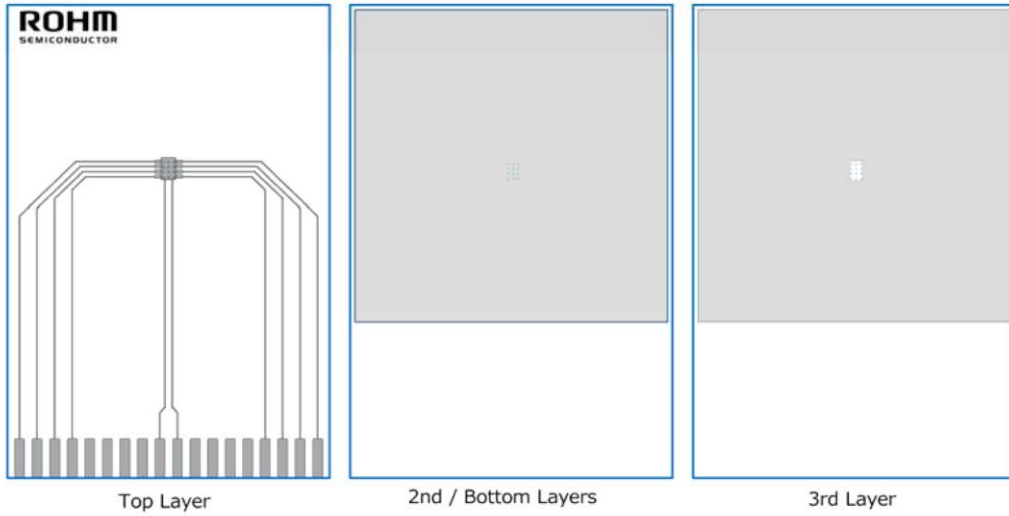
- PCB Layout 2 layers (2s)



Dimension	Value
Board Finish Thickness	1.60 mm \pm 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top/Bottom Layers)	0.070 mm (Cu + Plating)
Thermal Vias Separation/Diameter	1.2 mm / 0.3 mm

Thermal Resistance – continued

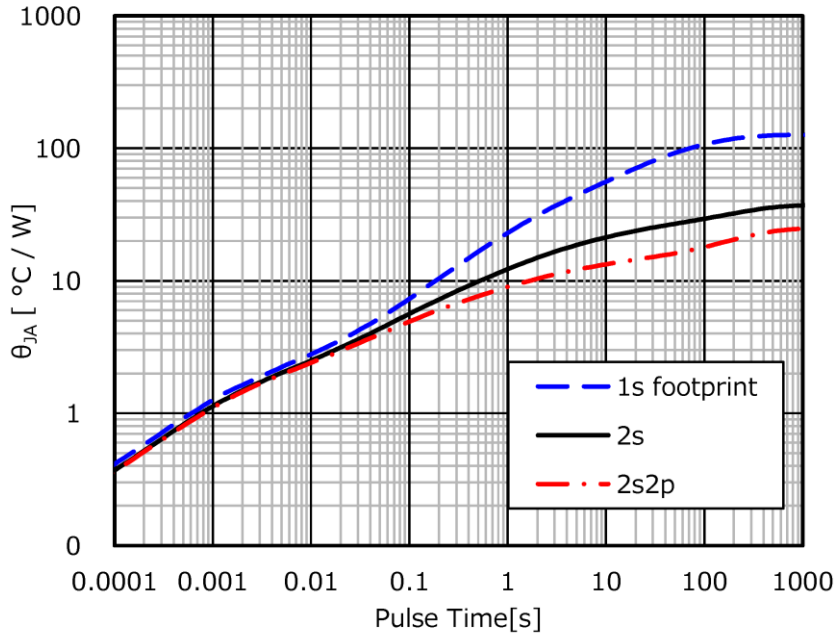
- PCB Layout 4 layers (2s2p)



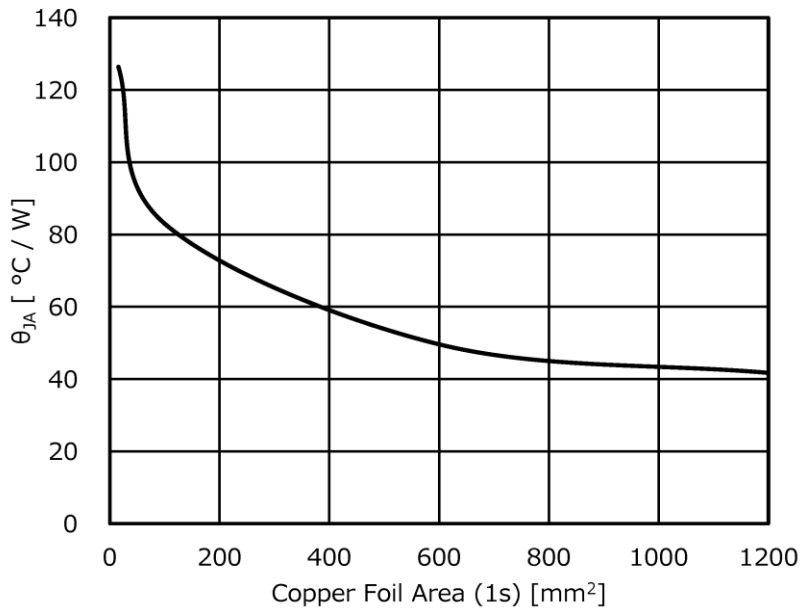
Dimension	Value
Board Finish Thickness	1.60 mm \pm 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top/Bottom Layers)	0.070 mm (Cu + Plating)
Thermal Vias Separation/Diameter	1.2 mm / 0.3 mm

Thermal Resistance – continued

- Thermal Resistance (Single Pulse)



- Thermal Resistance (θ_{JA} vs Copper foil area- 1s)



Electrical Characteristics

(Unless otherwise specified, $-40\text{ °C} \leq T_j \leq +150\text{ °C}$)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Output Clamp Voltage	$V_{OUT(CL)}$	42	48	54	V	$V_{IN} = 0\text{ V}$, $I_{OUT} = 1\text{ mA}$
On-state Resistance ($V_{IN} = 5\text{ V}$, $T_j = 25\text{ °C}$)	$R_{DS(ON)}$	-	85	120	m Ω	$V_{IN} = 5\text{ V}$, $I_{OUT} = 0.8\text{ A}$, $T_j = 25\text{ °C}$
On-state Resistance ($V_{IN} = 5\text{ V}$, $T_j = 150\text{ °C}$)	$R_{DS(ON)}$	-	155	210	m Ω	$V_{IN} = 5\text{ V}$, $I_{OUT} = 0.8\text{ A}$, $T_j = 150\text{ °C}$
On-state Resistance ($V_{IN} = 3\text{ V}$, $T_j = 25\text{ °C}$)	$R_{DS(ON)}$	-	115	150	m Ω	$V_{IN} = 3\text{ V}$, $I_{OUT} = 0.8\text{ A}$, $T_j = 25\text{ °C}$
On-state Resistance ($V_{IN} = 3\text{ V}$, $T_j = 150\text{ °C}$)	$R_{DS(ON)}$	-	195	270	m Ω	$V_{IN} = 3\text{ V}$, $I_{OUT} = 0.8\text{ A}$, $T_j = 150\text{ °C}$
Leak Current($T_j = 25\text{ °C}$)	$I_{OUT(L)}$	40	60	80	μA	$V_{IN} = 0\text{ V}$, $V_{OUT} = 18\text{ V}$, $T_j = 25\text{ °C}$
Leak Current($T_j = 150\text{ °C}$)	$I_{OUT(L)}$	50	85	200	μA	$V_{IN} = 0\text{ V}$, $V_{OUT} = 18\text{ V}$, $T_j = 150\text{ °C}$
Turn-ON TIME	t_{ON}	-	-	120	μs	$V_{IN} = 0\text{ V to } 5\text{ V}$, $R_L = 15\text{ }\Omega$, $V_{BAT} = 12\text{ V}$, $T_j = 25\text{ °C}$
Turn-OFF TIME	t_{OFF}	-	-	200	μs	$V_{IN} = 5\text{ V to } 0\text{ V}$, $R_L = 15\text{ }\Omega$, $V_{BAT} = 12\text{ V}$, $T_j = 25\text{ °C}$
Slew Rate On	SR_{ON}	-	0.3	0.6	V/ μs	$V_{IN} = 0\text{ V to } 5\text{ V}$, $R_L = 15\text{ }\Omega$, $V_{BAT} = 12\text{ V}$, $T_j = 25\text{ °C}$
Slew Rate Off	SR_{OFF}	-	0.4	0.8	V/ μs	$V_{IN} = 5\text{ V to } 0\text{ V}$, $R_L = 15\text{ }\Omega$, $V_{BAT} = 12\text{ V}$, $T_j = 25\text{ °C}$
Input Threshold Voltage	$V_{IN(TH)}$	1.5	-	2.7	V	$R_L = 15\text{ }\Omega$, $V_{BAT} = 12\text{ V}$
High-level Input Current1(in Normal Operation)	$I_{IN(H1)}$	-	110	220	μA	$V_{IN} = 5\text{ V}$
High-level Input Current2(in Abnormal Operation) *1	$I_{IN(H2)}$	-	-	500	μA	$V_{IN} = 5\text{ V}$
Low-level Input Current	$I_{IN(L)}$	-10	0	+10	μA	$V_{IN} = 0\text{ V}$
Over Current Limitation Level	$I_{OUT(LIM)}$	4.0	5.5	7.0	A	$V_{IN} = 5\text{ V}$, $V_{BAT} = 12\text{ V}$, $T_j = 25\text{ °C}$
Thermal Shutdown Operated Temperature *2	T_{TSDD}	150	175	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$
Thermal Shutdown Released Temperature *2	T_{TSDR}	135	-	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$
Thermal Shutdown Hysteresis *2	T_{TSDHYS}	-	15	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$

*1 When thermal shutdown function or over current protection function is ON.

*2 Not 100 % tested.

Electrical Characteristics – continued

(Unless otherwise specified, $-40\text{ °C} \leq T_j \leq +150\text{ °C}$)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Open Load Detection Voltage	V_{OPEN}	1.5	-	4.5	V	$V_{IN} = 0\text{ V}$, $V_{DD} = 5\text{ V}$, $R_{ST} = 10\text{ k}\Omega$
ST Output On Voltage 1	$V_{ST(ON1)}$	-	0.2	0.5	V	$V_{IN} = 5\text{ V}$, $I_{ST} = 1\text{ mA}$
ST Output On Voltage 2	$V_{ST(ON2)}$	-	0.2	0.5	V	$V_{IN} = 0\text{ V}$, $V_{OUT} = 4.5\text{ V}$, $I_{ST} = 0.5\text{ mA}$
ST Output Leak Current 1	$I_{ST(L1)}$	-	-	20	μA	$V_{IN} = 5\text{ V}$, $V_{ST} = 5\text{ V}$
ST Output Leak Current 2	$I_{ST(L2)}$	-	-	20	μA	$V_{IN} = 0\text{ V}$, $V_{OUT} = 1.5\text{ V}$, $V_{ST} = 5\text{ V}$
ST Output Delay Time Detect	t_{STDET}	-	1	30	μs	$V_{IN} = 0\text{ V}$, $V_{OUT} = 5\text{ V to } 1\text{ V}$, $V_{DD} = 5\text{ V}$, $R_{ST} = 10\text{ k}\Omega$, $C_{ST} = 10\text{ pF}$
ST Output Delay Time Release	t_{STREL}	-	1	30	μs	$V_{IN} = 0\text{ V}$, $V_{OUT} = 1\text{ V to } 5\text{ V}$, $V_{DD} = 5\text{ V}$, $R_{ST} = 10\text{ k}\Omega$, $C_{ST} = 10\text{ pF}$

Typical Performance Curves

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

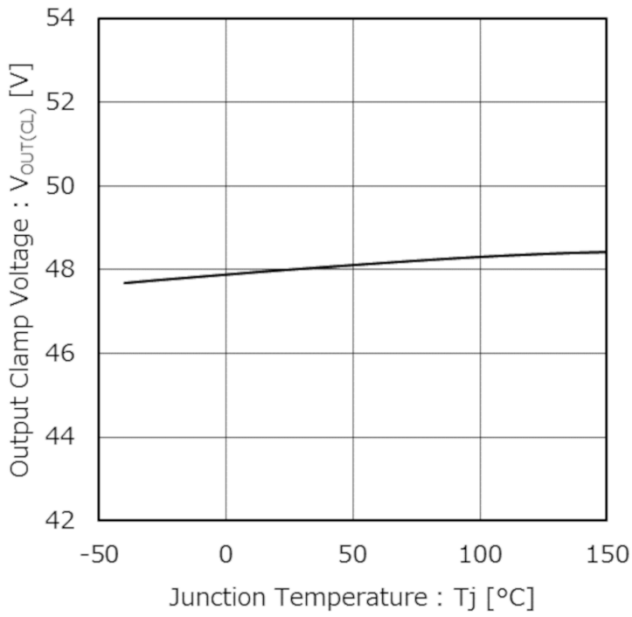


Figure 2. Output Clamp Voltage vs Junction Temperature

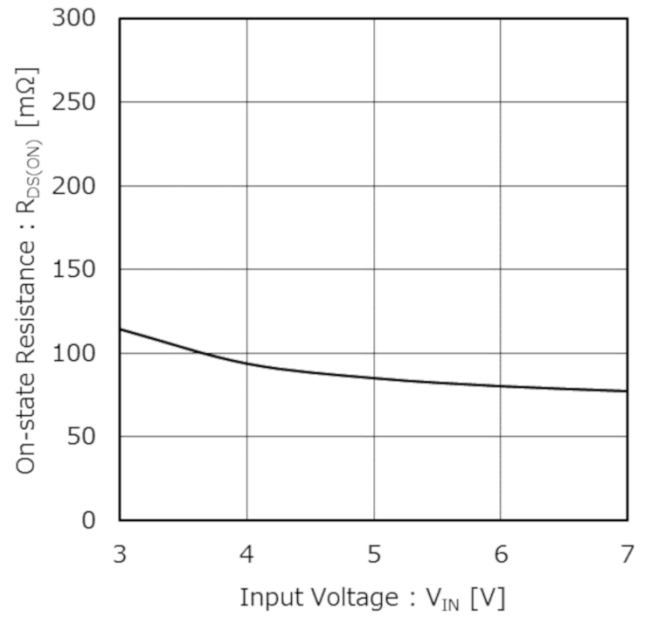


Figure 3. On-state Resistance vs Input Voltage

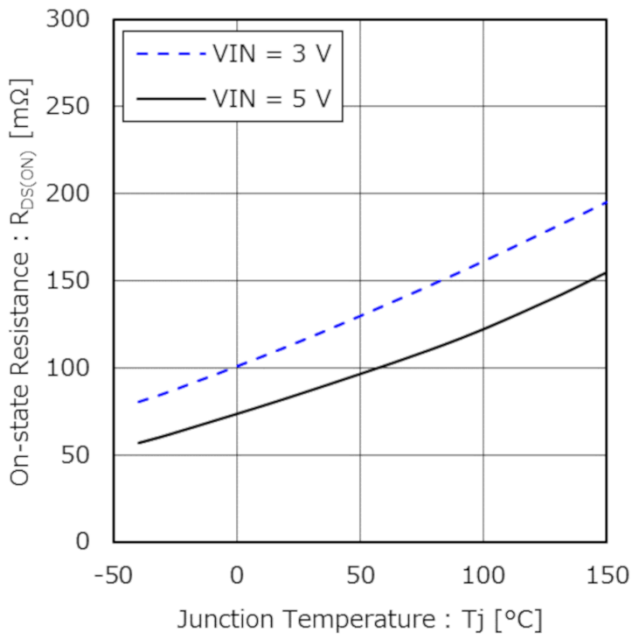


Figure 4. On-state Resistance vs Junction Temperature

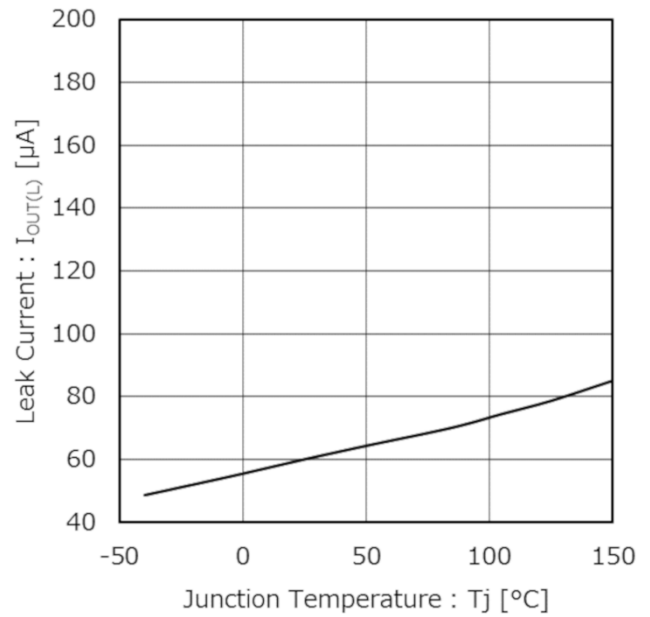


Figure 5. Leak Current vs Junction Temperature

Typical Performance Curves – continued

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

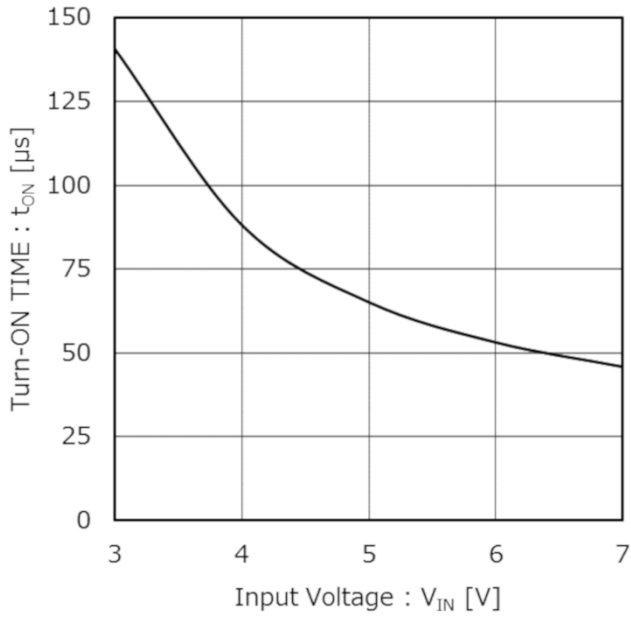


Figure 6. Turn-ON TIME vs Input Voltage

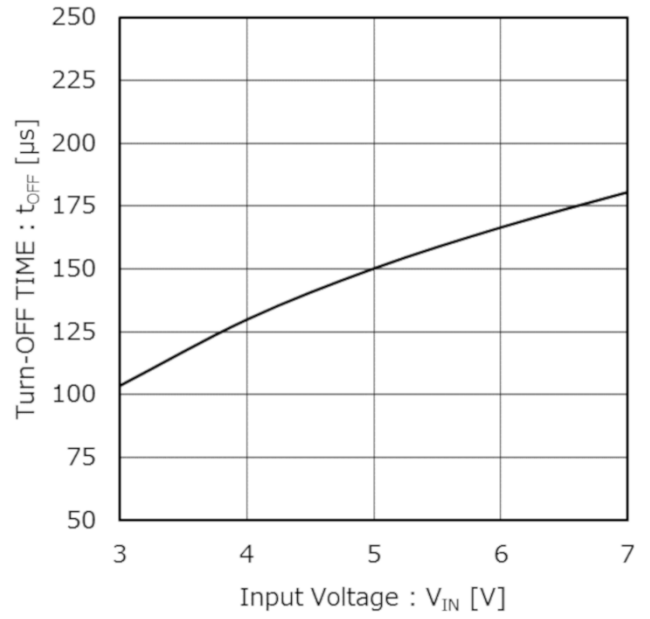


Figure 7. Turn-OFF TIME vs Input Voltage

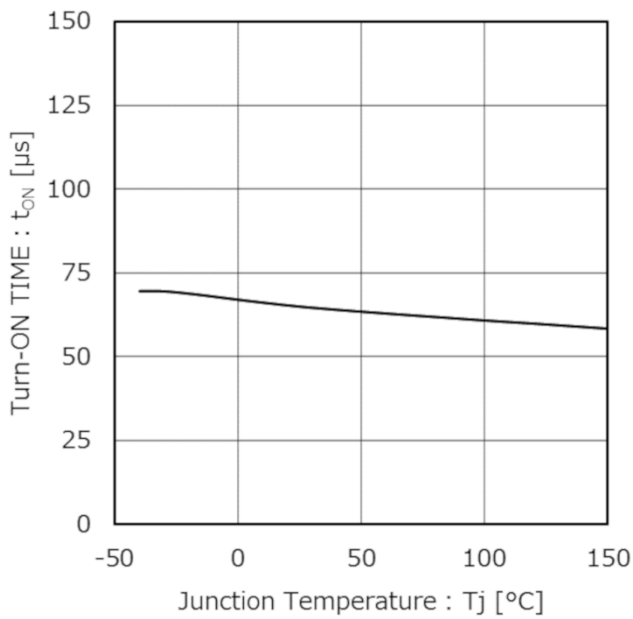


Figure 8. Turn-ON TIME vs Junction Temperature

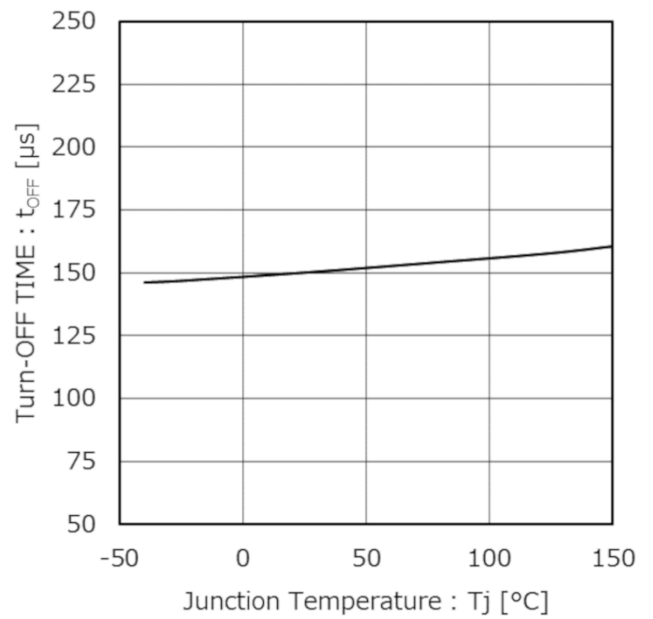


Figure 9. Turn-OFF TIME vs Junction Temperature

Typical Performance Curves – continued

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

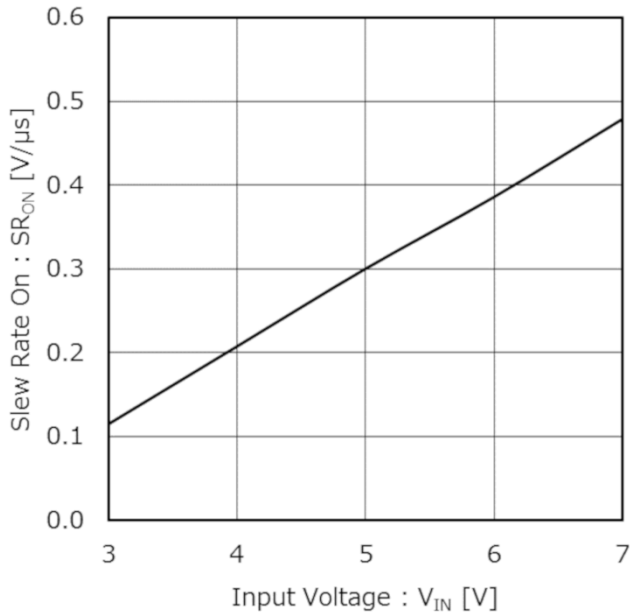


Figure 10. Slew Rate On vs Input Voltage

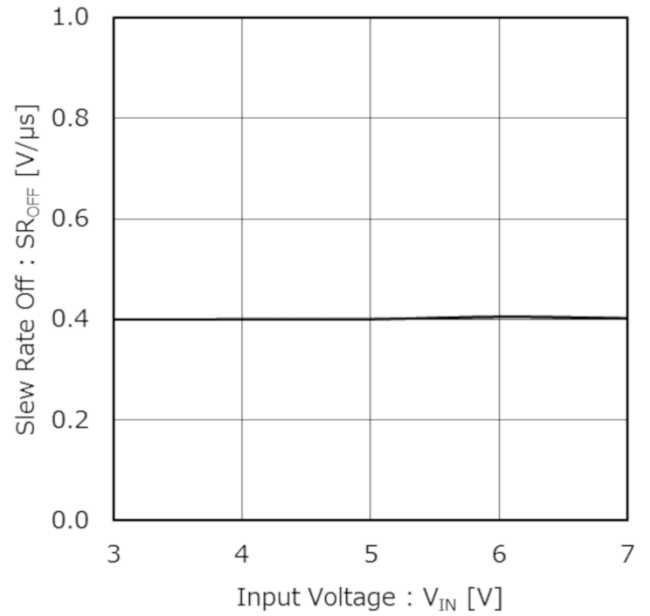


Figure 11. Slew Rate Off vs Input Voltage

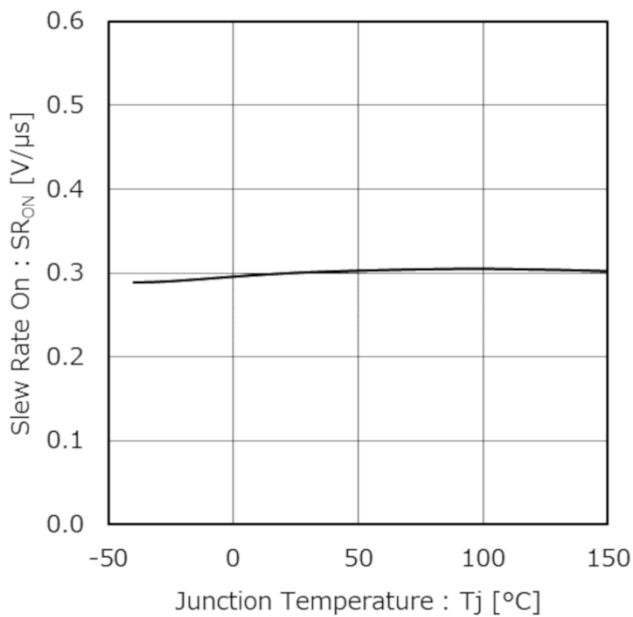


Figure 12. Slew Rate On vs Junction Temperature

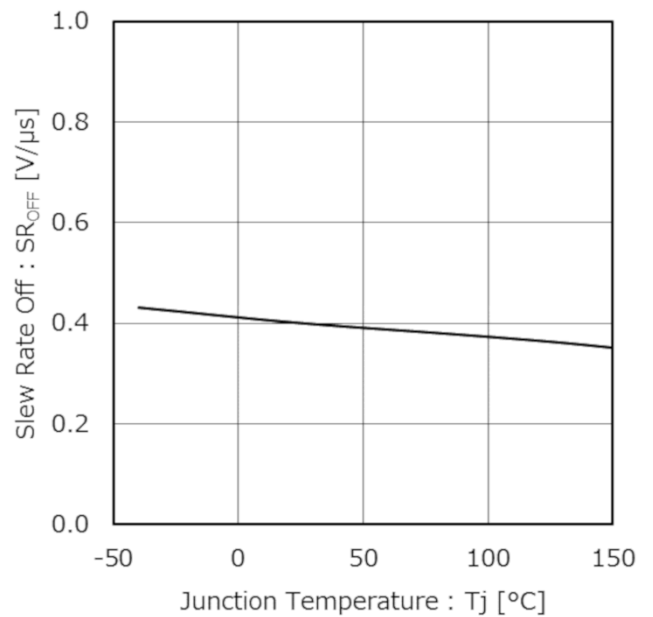


Figure 13. Slew Rate Off vs Junction Temperature

Typical Performance Curves – continued

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

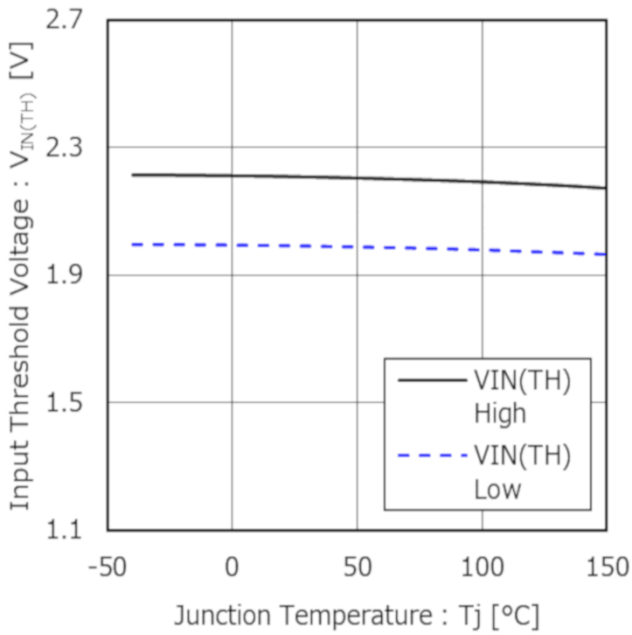


Figure 14. Input Threshold Voltage vs Junction Temperature

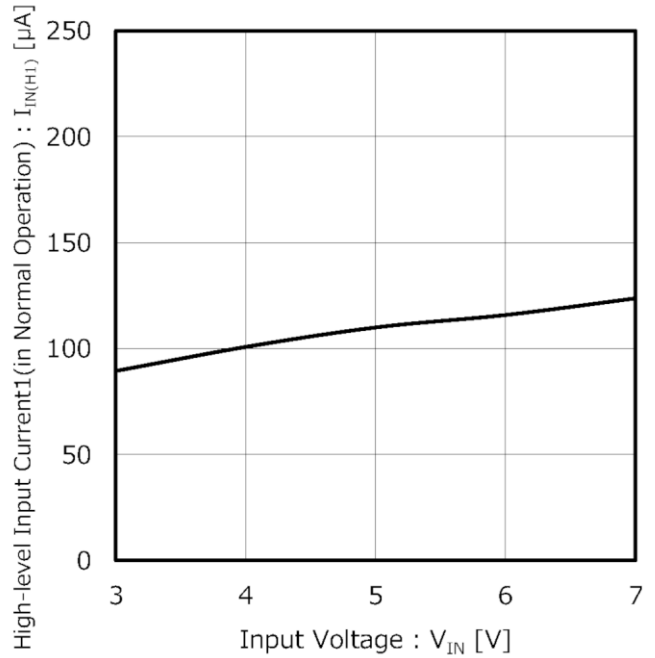


Figure 15. High-level Input Current1(in Normal Operation) vs Input Voltage

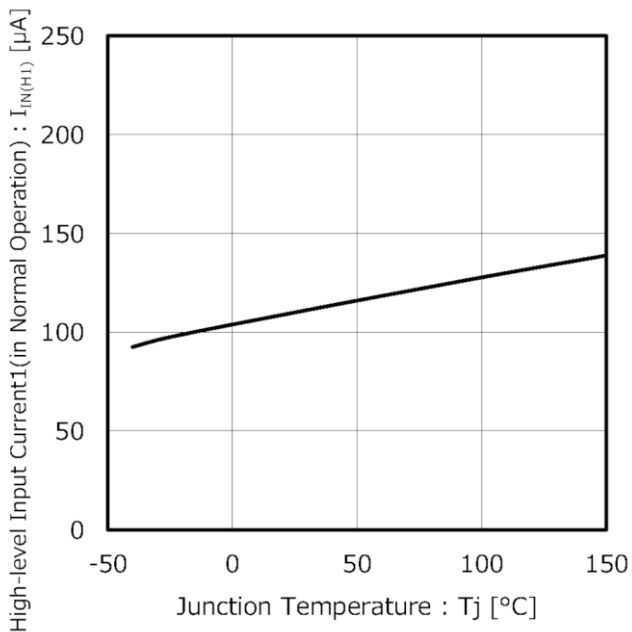


Figure 16. High-level Input Current1(in Normal Operation) vs Junction Temperature

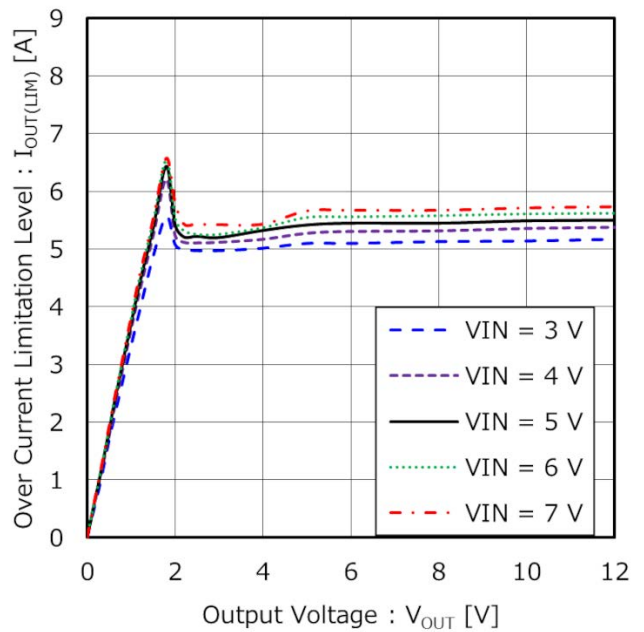


Figure 17. Over Current Limitation Level vs Output Voltage

Typical Performance Curves – continued

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

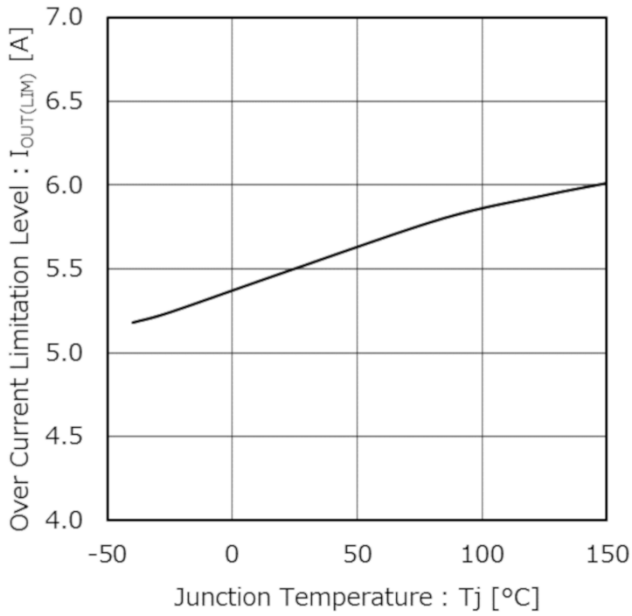


Figure 18. Over Current Limitation Level vs Junction Temperature

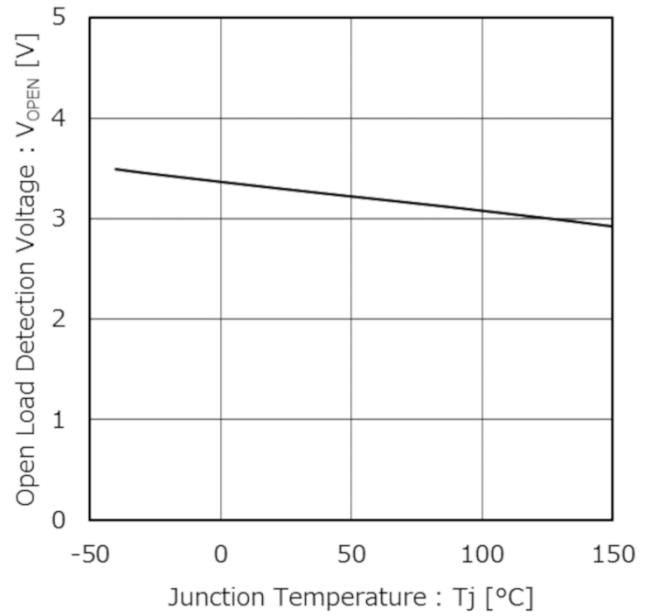


Figure 19. Open Load Detection Voltage vs Junction Temperature

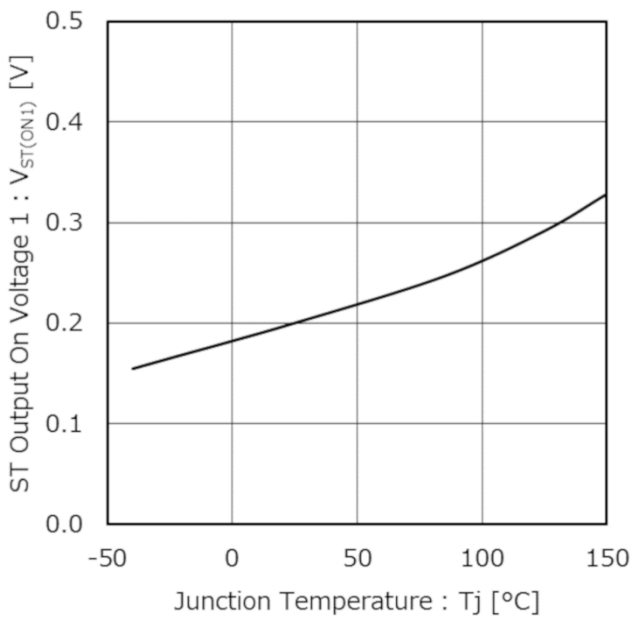


Figure 20. ST Output On Voltage 1 vs Junction Temperature

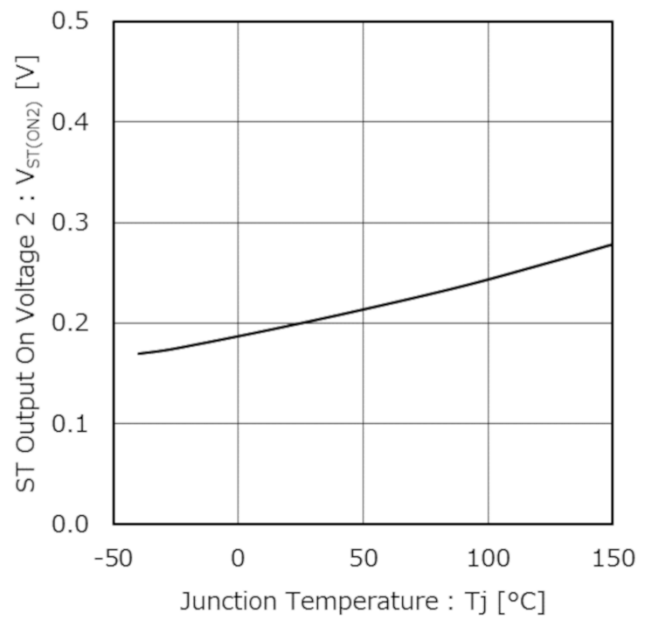


Figure 21. ST Output On Voltage 2 vs Junction Temperature

Typical Performance Curves – continued

(Unless otherwise specified, $T_j = 25\text{ }^\circ\text{C}$, $V_{IN} = 5.0\text{ V}$)

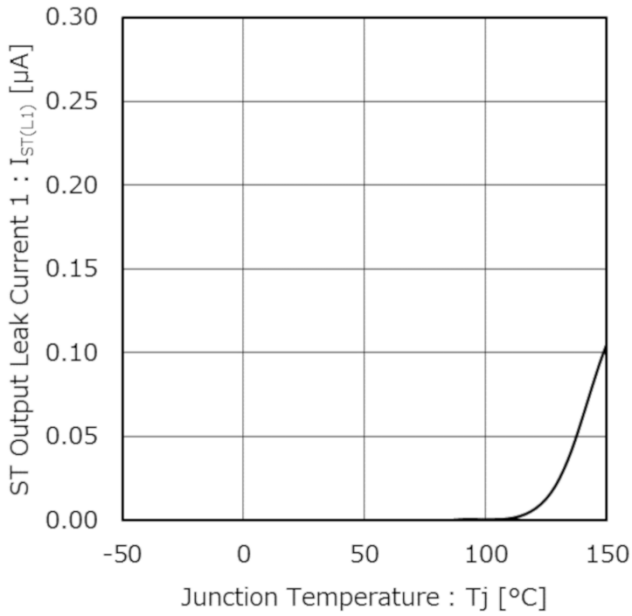


Figure 22. ST Output Leak Current 1 vs Junction Temperature

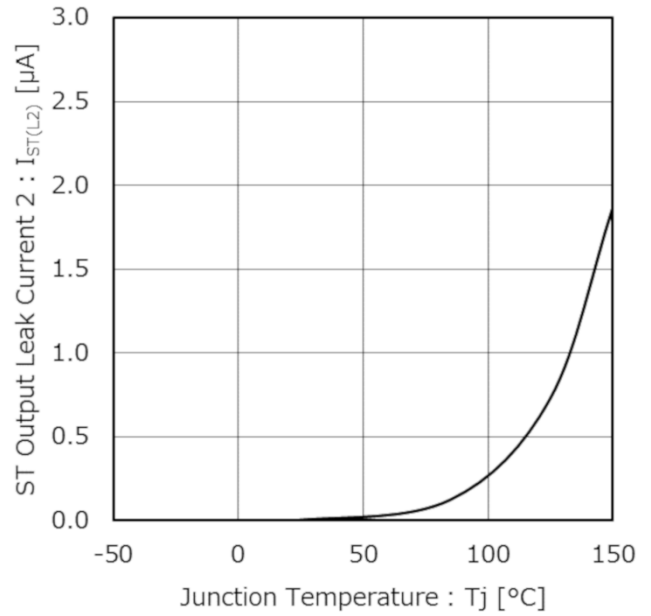


Figure 23. ST Output Leak Current 2 vs Junction Temperature

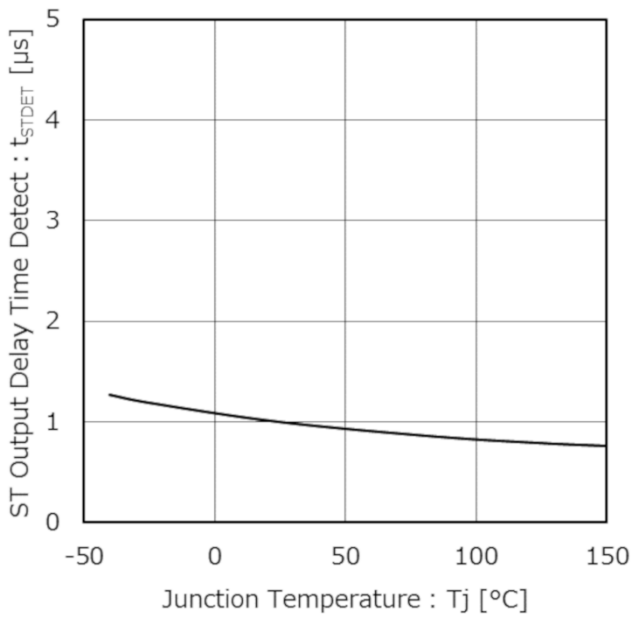


Figure 24. ST Output Delay Time Detect vs Junction Temperature

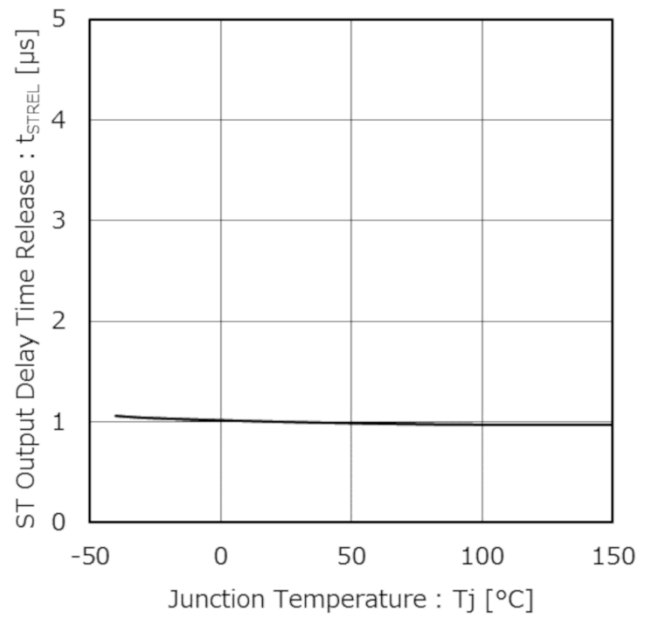
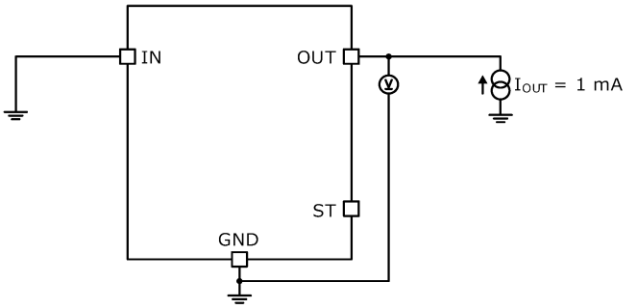
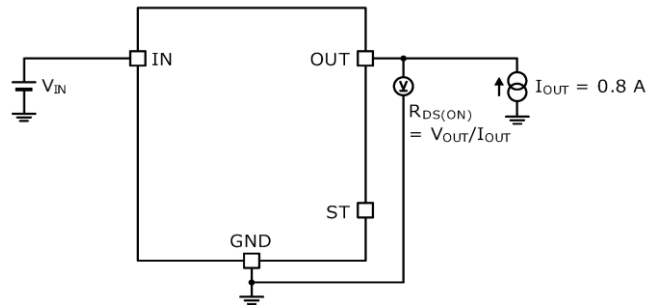


Figure 25. ST Output Delay Time Release vs Junction Temperature

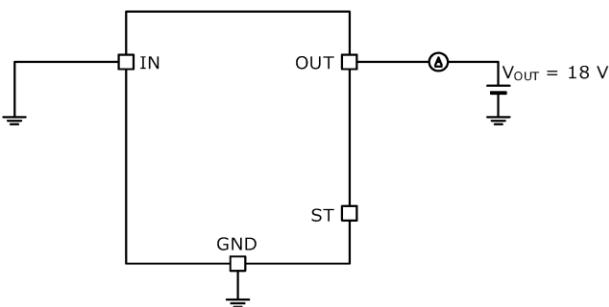
Measurement Circuit for Typical Performance Curves



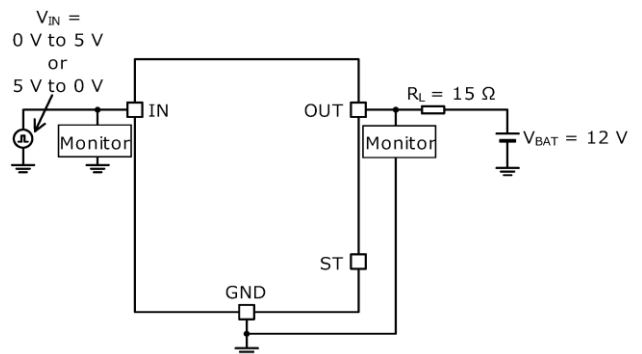
Measurement Circuit for Figure 2



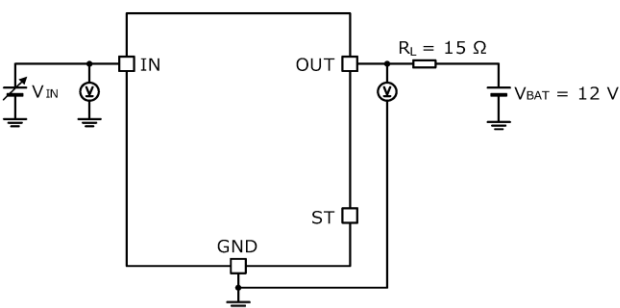
Measurement Circuit for Figure 3 and Figure 4



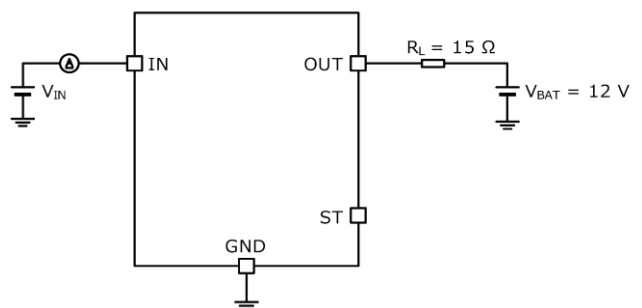
Measurement Circuit for Figure 5



Measurement Circuit for Figure 6, Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12 and Figure 13

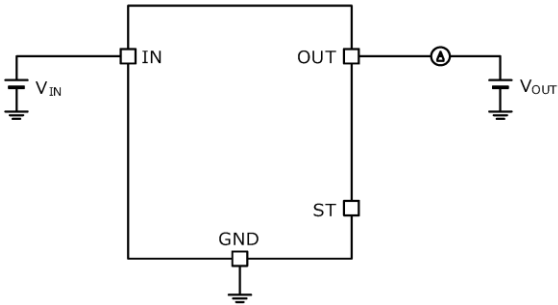


Measurement Circuit for Figure 14

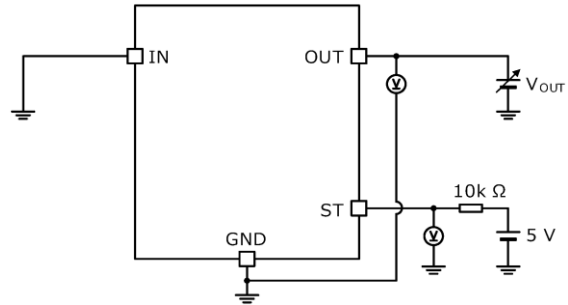


Measurement Circuit for Figure 15 and Figure 16

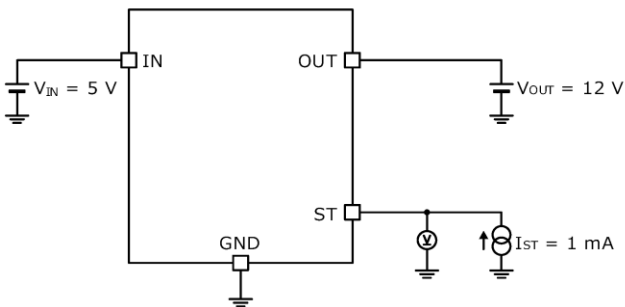
Measurement Circuit for Typical Performance Curves – continued



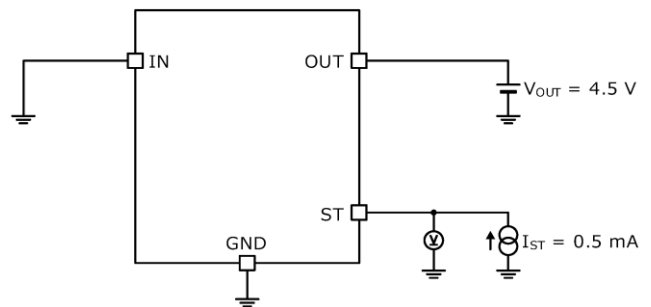
Measurement Circuit for Figure 17 and Figure 18



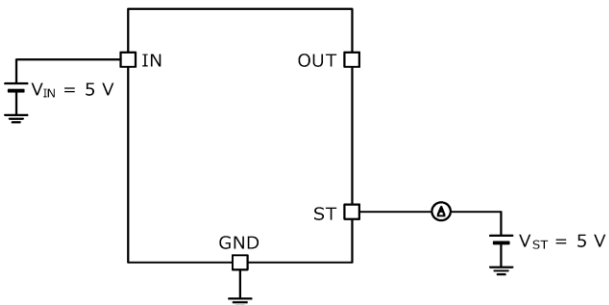
Measurement Circuit for Figure 19



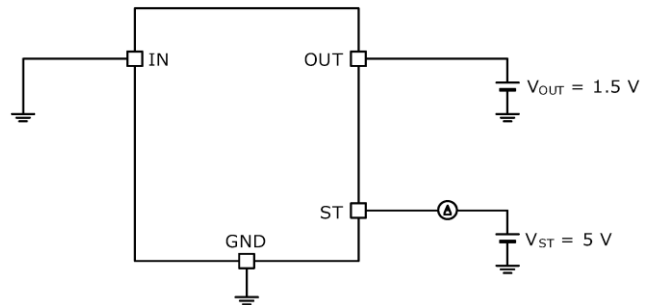
Measurement Circuit for Figure 20



Measurement Circuit for Figure 21

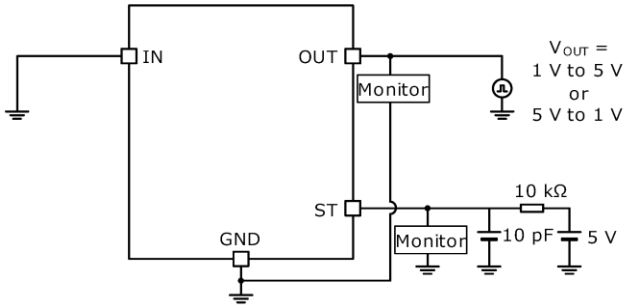


Measurement Circuit for Figure 22



Measurement Circuit for Figure 23

Measurement Circuit for Typical Performance Curves – continued



Measurement Circuit for Figure 24 and Figure 25

I/O Pin Truth Table

■ Output Function

Priority	Input Signal	Operating Status	Output Status
1	Low	Standby	OFF
2	High	Over Temperature	OFF
3	High	Over Current	Current Limiting
4	High	Normal	ON

■ Diagnostic Function of Abnormal Status

Diagnoses the presence or absence of an abnormal condition. By combining High and Low of the input signal and the ST pin, it is possible to grasp overcurrent, heating state, load open state.

Input Signal	ST Signal	Diagnosis Result
Low	Low	No Abnormality
Low	High	Load Open
High	Low	Over Current or Over Temperature
High	High	No Abnormality

Timing Chart

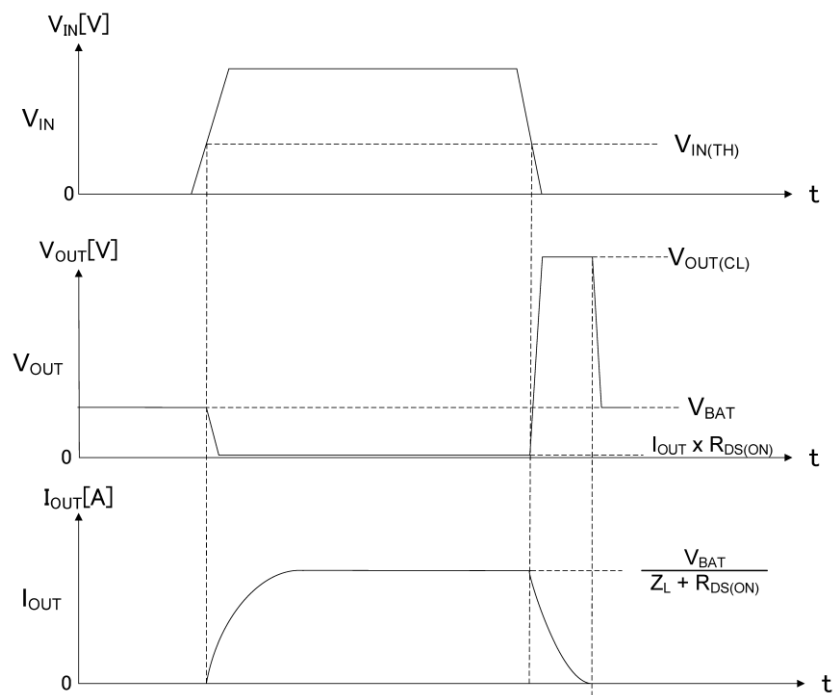


Figure 26. Inductive Load Operation

Timing Chart – continued

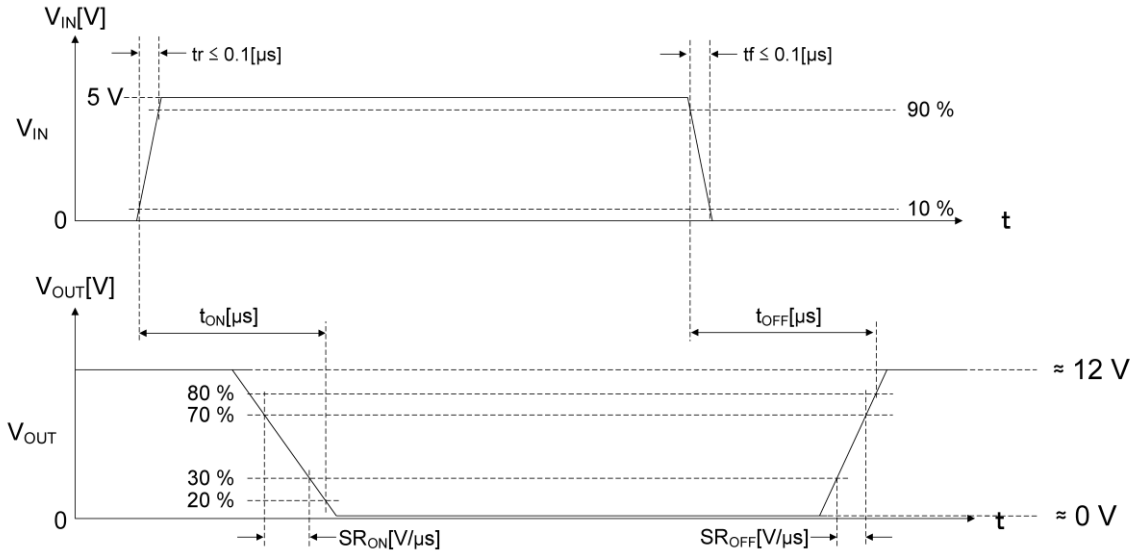


Figure 27. Term of Turn-ON TIME, Turn-OFF TIME and Slew Rate

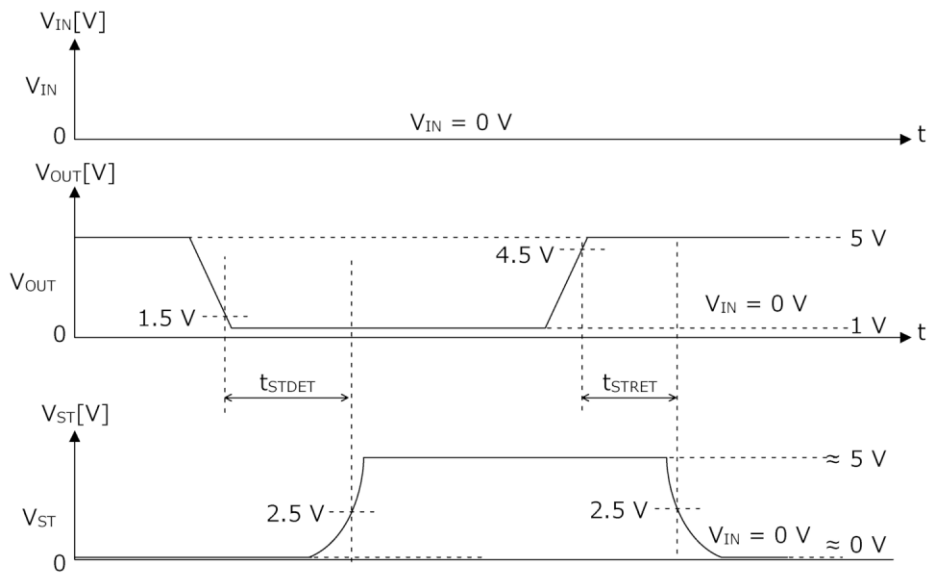


Figure 28. ST Output Delay Time

Function Description

■ Over Current Protection Function

This IC has OCP function. Following is shown that the timing chart of OCP function.

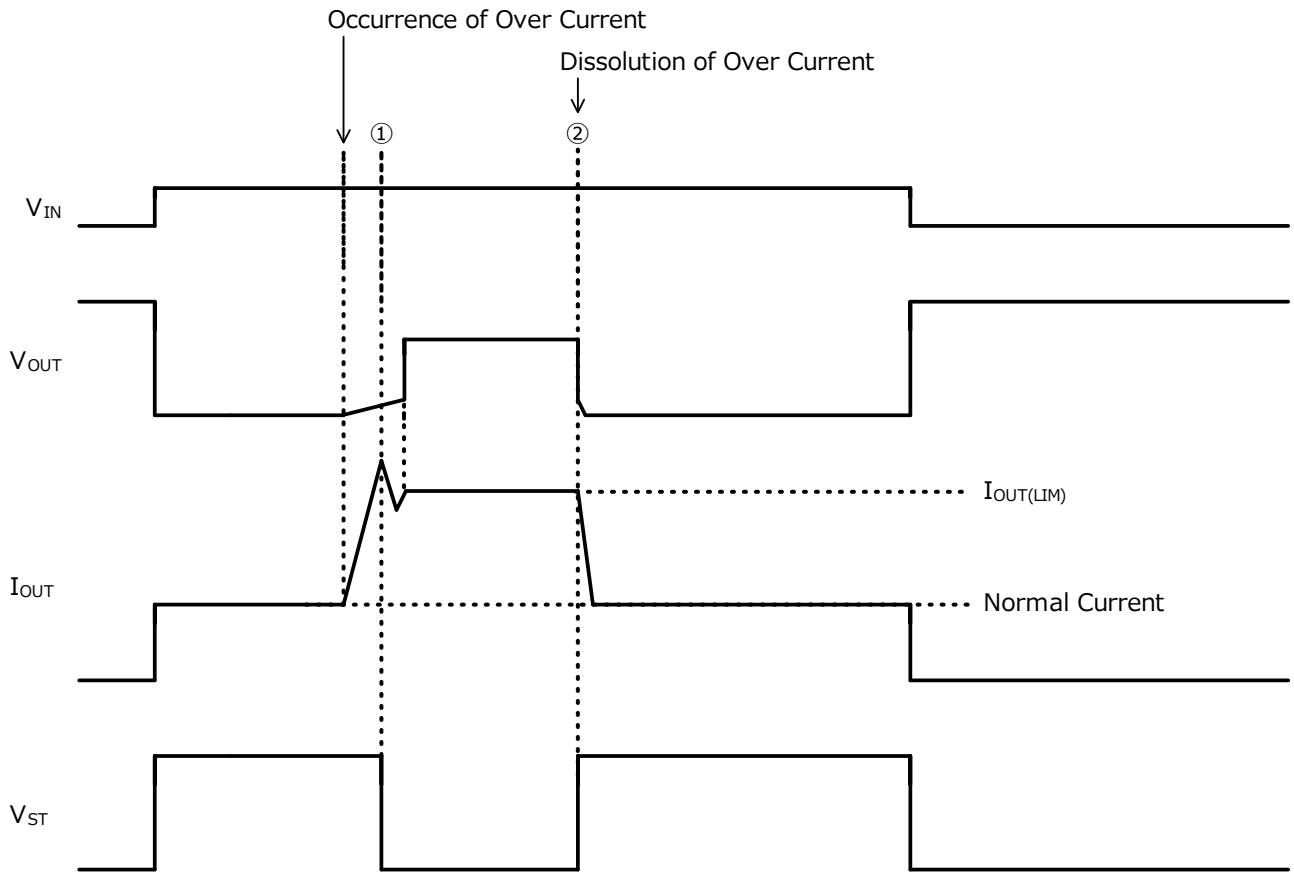


Figure 29. Timing Chart of OCP Function

- ① I_{OUT} is limited at Over Current Limitation Level ($I_{OUT(LIM)} = 5.5 \text{ A (Typ)}$) and the V_{OUT} rises when over current is occurred. The presense of an abnormal of condition is detected and V_{ST} turns Low.
- ② Current limitation is released when over current is occurred. The presense of an abnormal of condition is released and V_{ST} turns High.

Function Description – continued

■ TSD Function

This IC has a built-in TSD function. Following is shown that the timing chart of TSD function.

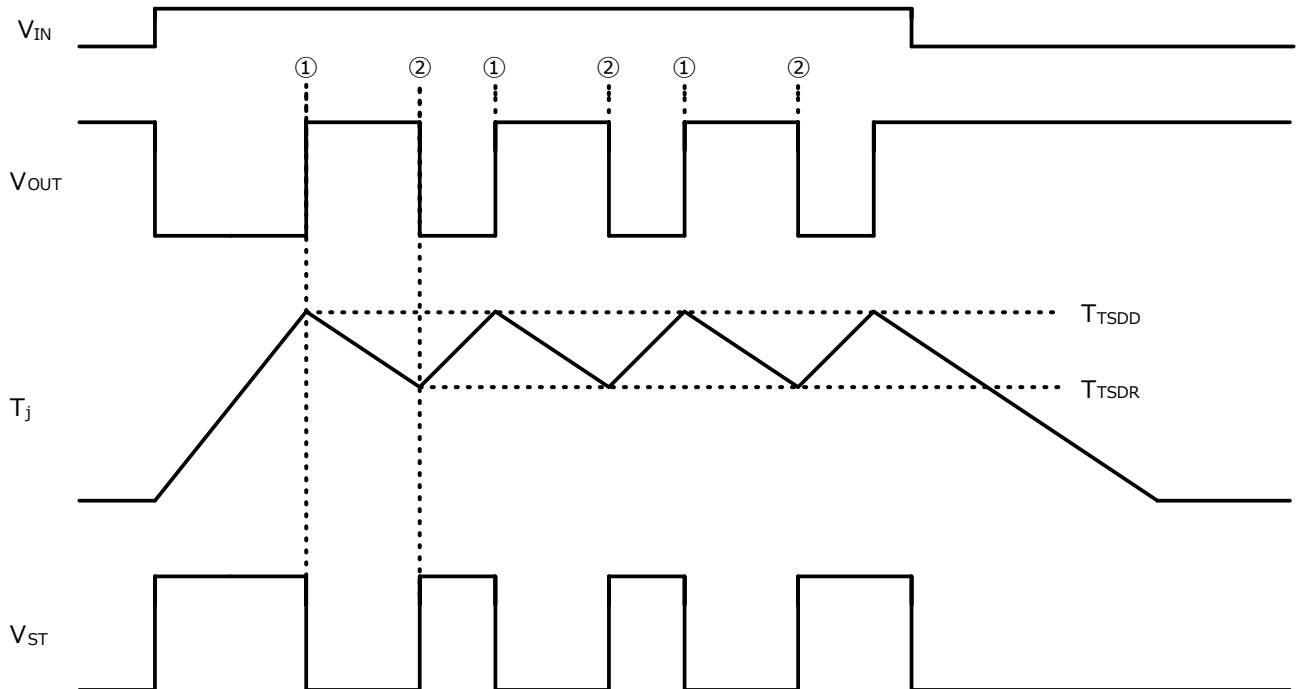


Figure 30. Timing Chart of TSD Function

- ① The output is turned off when the temperature of the IC reaches Thermal Shutdown Operated Temperature (T_{TSDD}) = 175 °C (Typ) or more. The presence of an abnormal condition is detected and V_{ST} turns Low.
- ② The output returns to its normal state when the temperature of the IC becomes Thermal Shutdown Released Temperature (T_{TSDR}) = 135 °C (Min) or less. The presence of an abnormal condition is released and V_{ST} turns High.

Operational Notes

1. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

2. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

3. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

4. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

5. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

6. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

7. Thermal Shutdown Function (TSD)

This IC has a built-in thermal shutdown function that prevents heat damage to the IC. Normal operation should always be within the IC's maximum junction temperature rating. If however the rating is exceeded for a continued period, the junction temperature (T_j) will rise which will activate the TSD function that will turn OFF power output pins. When the T_j falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD function operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD function be used in a set design or for any purpose other than protecting the IC from heat damage.

8. Over Current Protection Function (OCP)

This IC incorporates an integrated over current protection function that is activated when the load is shorted. This protection function is effective in preventing damage due to sudden and unexpected incidents. However, the IC should not be used in applications characterized by continuous operation or transitioning of the protection function.

9. Active Clamp Operation

The IC integrates the active clamp function to internally absorb the reverse energy which is generated when the inductive load is turned off. When the active clamp operates, the thermal shutdown function does not work. Decide a load so that the reverse energy is active clamp tolerance [refer to Figure 1] or under when inductive load is used.

Operational Notes – continued

10. Negative Current of Output

When the OUT pin (DRAIN) becomes lower than the GND pin (SOURCE), a current flow from the in pin (the IN pin) to the OUT pin (DRAIN) through a parasitic transistor. As shown in Figure 31 when the input pin is High, a current flow from a power supply of the connection (MCU, and so on) of the input pin to the OUT pin (DRAIN). As shown in Figure 32 when the input pin is Low, a current flow from the GND of parts (MCU, and so on) that connected to the input pin to the OUT pin (DRAIN).

Therefore, set the OUT pin (DRAIN) is -0.3 V or higher. When the OUT pin becomes lower than -0.3 V , add a restriction resistance $330\ \Omega$ or higher to the IN pin. However, set the value of restriction resistance in consideration of the voltage descent caused by power supply pin and input pins currents.

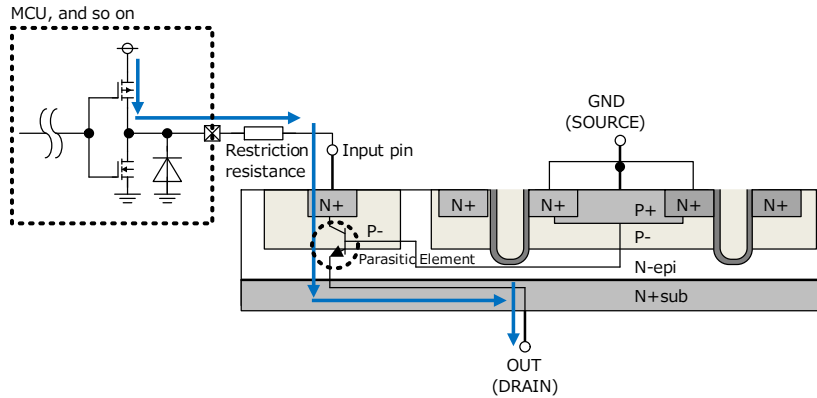


Figure 31. Negative Current Path (when the input pins are High)

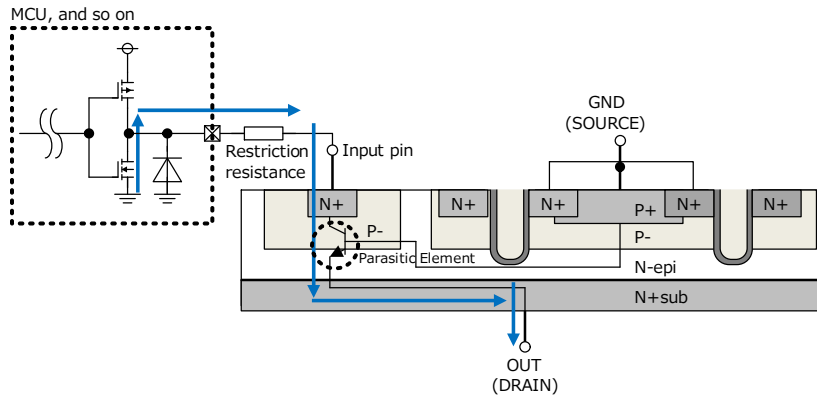


Figure 32. Negative Current Path (when the input pins are Low)

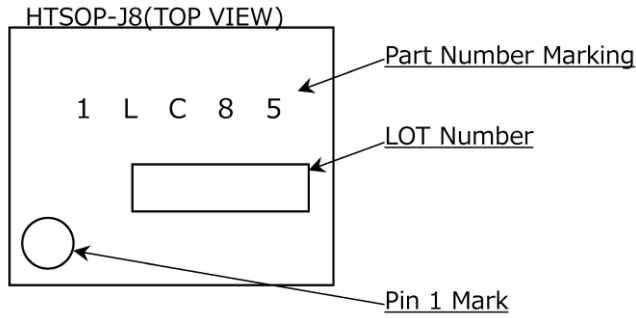
Ordering Information

B V 1 L C 0 8 5 E F J - C E 2

Package
EFJ : HTSOP-J8

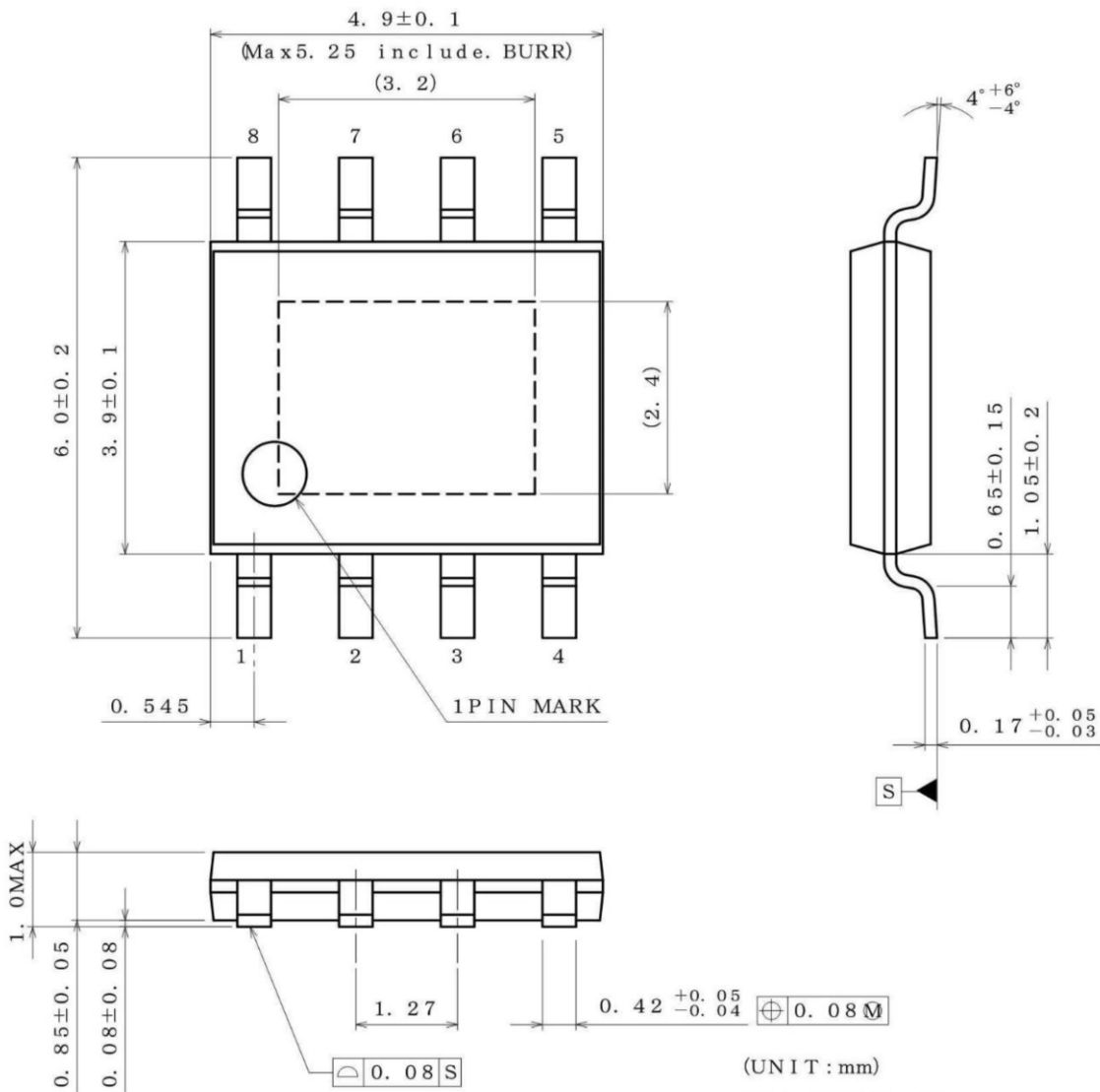
Product Rank
C: for Automotive
Packaging and forming specification
E2: Embossed tape and reel

Marking Diagram



Physical Dimension and Packing Information

Package Name	HTSOP-J8
--------------	----------



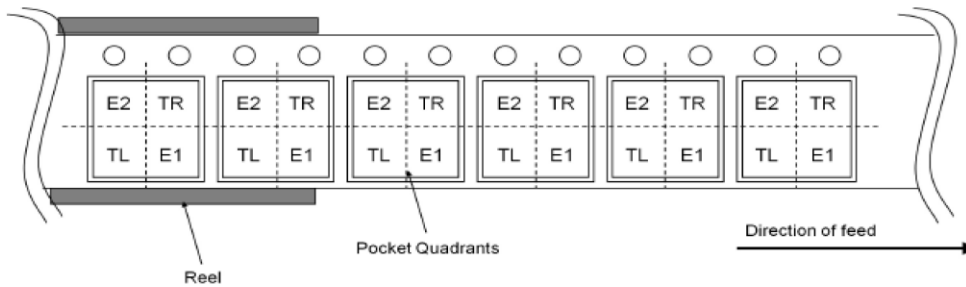
(UNIT : mm)

PKG : HTSOP-J8

Drawing No. EX169-5002-2

<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



Revision History

Date	Revision	Changes
30.Sep.2020	001	New Release
23.Jun.2021	002	Correction of typographical errors on "ST Output Leak Current 2" condition in the electrical characteristics item. Correction of typographical errors on "TSD Function/②/Thermal Shutdown Released Temperature" condition in the Function Description.

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
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